

HYPERBGA BUILDUP LAMINATE

Abstract of the Disclosure

A method and structure for forming an electronic structure that comprises a redistribution structure on a circuitized substrate. The redistribution structure includes N dielectric layers ($N \geq 2$) and N metal planes formed in the following sequence: dielectric layer 1 on a metallic plane that exists on a surface of the substrate, metal plane 1 on dielectric layer 1, dielectric layer 2 on dielectric layer 1 and metal plane 1, metal plane 2 on the dielectric layer 2, ..., dielectric layer N on dielectric layer N-1 and metal plane N-1, and metal plane N on the dielectric layer N. Metal planes or metallic planes may include signal planes, power planes, ground planes, etc. A microvia structure, which is formed through the N dielectric layers and electrically couples metal plane N to the metallic plane, includes a microvia or a portion of a microvia through each dielectric layer.